

LTM8067 38LD BGA-PBF 11.25mm X 9mm X 4.92mm (TABLE OF MATERIAL DECLARATION)

This Package is RoHS compliant per EU RoHS Directive 2003/95/EC.
It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+) polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.0967	Bismaleimide/Triazine Resin/Filler Substances (Silica Crystalline)	105391-33-1 1156-51-0/9003-36-5/21645-51-2 *non-disclosure	0.01810	18.72
				Continuous Filament Fiber Glass	65997-17-3	0.01605	16.60
				Copper Metal	7440-50-8	0.04954	51.25
				Zinc	7440-66-6	0.00000	0.01
				Chromium(III) oxide	1308-38-9	0.00000	0.00
				Epoxy Resin	*non-disclosure	0.00001	0.01
				Barium Compounds	7727-43-7	0.00380	3.93
				Silica amorphous	7631-86-9	0.00006	0.07
				Calcium cacbonate	471-34-1	0.00000	0.00
				Amine compounds	*non-disclosure	0.00006	0.06
				Leveling agent and others	*non-disclosure	0.00017	0.17
				Acrylic Resin	*non-disclosure	0.00725	7.50
				Copper Compounds	147-14-8	0.00003	0.03
				Talc;not containing fibers like asbestos	14807-96-6	0.00044	0.45
				Aromatic carbonyl compounds	non-disclosure	0.00041	0.43
				Cyanoguanidine	461-58-5	0.00001	0.01
				Nickel	7440-02-0	0.00058	0.60
				Gold	7440-57-5	0.00012	0.13
				**Ecotoxic substances	7440-38-2 7440-28-0	0.00002	0.02
				2	Solder Paste	Alloy	0.0011
Antimony (Sb)	7440-36-0	0.00005	5.00				
3	Components	Passive/Active	0.2476	Iron Powder (Fe)	7439-89-6	0.00000	0.00
				Copper (Cu)	7440-50-8	0.07923	32.00
				Nickel (Ni)	7440-02-0	0.01981	8.00
				Tin (Sn)	7440-31-5	0.00594	2.40
				Ceramic (Ba) Compounds	12047-27-7	0.14261	57.60
4	Active Ics	Silicon	0.0024	Silicon (Si)	7440-21-3	0.00236	100.00
5	Wire	Gold	0.0118	Gold (Au)	7440-57-5	0.01177	99.99
6	Solder Ball	Alloy	0.0732	Tin (Sn)	7440-31-5	0.07061	96.50
				Silver (Ag)	7440-22-4	0.00220	3.00
				Copper (Cu)	7440-50-8	0.00037	0.50
7	Encapsulation	Epoxy Resin	0.7148	Fused Silica	60676-86-0	0.55182	77.20
				Epoxy Resin	non-disclosure	0.06362	8.90
				Phenol Resin	non-disclosure	0.06362	8.90
				Crytalline Silica	14808-60-7	0.02144	3.00
				Carbon Black	1333-86-4	0.00357	0.50
				Metal Hydroxide	non-disclosure	0.01072	1.50
Total Package Weight			1.1474				

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts